

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT7480532

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
RUDI BLUMENSCHNEIN	08/01/2022
FRANK KAEHNY	06/24/2022
MANUEL EHEIM	07/07/2022
RECEIVING PARTY DATA	
Name:	TE CONNECTIVITY GERMANY GMBH
Street Address:	AMPERESTRASSE 12-14
City:	BENSHEIM
State/Country:	GERMANY
Postal Code:	64625
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17695448
CORRESPONDENCE DATA	
Fax Number:	(610)889-3696
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	610-889-3699
Email:	berwynipdocket@barley.com
Correspondent Name:	BARLEY SNYDER
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Address Line 2:	SUITE 110
Address Line 4:	MALVERN, PENNSYLVANIA 19355
ATTORNEY DOCKET NUMBER:	21334-3430
NAME OF SUBMITTER:	SALVATORE ANASTASI
SIGNATURE:	/Salvatore Anastasi/
DATE SIGNED:	08/11/2022
Total Attachments: 2	
source=signedDelcFrankManuel#page1.tif	
source=signedDelcRudi#page1.tif	

COMBINED DECLARATION AND ASSIGNMENT

As a below named and signing inventor, I hereby declare that:

this declaration is directed to inventions and improvements disclosed in:

- the attached application, or
- United States application or PCT international application number _____ filed on _____,
entitled Arrangement for Making A Diffusion Solder Connection Between an Electrically
Conductive Contact Element and a Workpiece ("the APPLICATION");

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

As a below named and signing inventor, acknowledging that I have assigned or have obligations to assign the APPLICATION to:

TE Connectivity Germany GmbH ("ASSIGNEE"), a corporation organized and existing under and by virtue of the laws of Germany, having its principal place of business at Amperestrasse 12-14, Bensheim, Germany D-64625,

for a valuable consideration, the receipt of which is hereby acknowledged, I do hereby sell, assign, transfer, and set over unto the said ASSIGNEE, its successors and assigns, my full and entire right, title and interest in and to the APPLICATION, the inventions and improvements disclosed in the APPLICATION, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent to be granted and issued therefor, not only for, to and in the United States of America, its territories and possessions, but also for, to and in all other countries, including all priority rights under the International Convention, and all reissues, re-examinations, renewals or extensions thereof; and I hereby authorize and request the United States Patent and Trademark Office and/or other patent office(s) to issue said Letters Patent to said ASSIGNEE, its successors and assigns, in accordance with this assignment.

Legal Name	Signature	Date
Rudi Blumenschein		
Frank Kaehny	<i>Frank Kaehny</i>	24.06.2022
Manuel Eheim	<i>Manuel Eheim</i>	07.06.2022

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- the attached application, or
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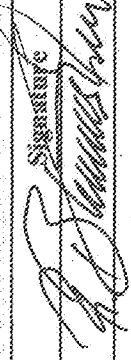
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Legal Name	Signature	Date
Rudi Blumenschein		8.1.22
Frank Kaehny		
Manuel Eheim		